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Specification for Metal Base Copper Clad Laminates for Rigid Printed Boards

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the English version will
take precedence.

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Table of Contents

1	SCOPE	1	2.7	ASTM International	6
1.1	Purpose	1	2.7.1	ASTM D5470-1	6
1.2	Classification	1	2.8	JEDEC	6
1.3	Measurement Units	1	2.8.1	JESD557	6
1.4	Definition of Requirements	1	3	REQUIREMENTS	7
1.5	Process Control Requirements	1	3.1	Requirement Definitions	7
1.6	Order of Precedence	2	3.1.1	Qualification Assessment	7
1.6.1	Conflict	2	3.1.2	Quality Conformance Testing	7
1.6.2	Clause References	2	3.1.3	Manufacturer's Quality System	7
1.6.3	Appendices.....	2	3.1.4	Process Control Testing	7
1.6.3.1	Appendix A	2	3.1.5	Self Declaration	7
1.7	Use of "Lead"	2	3.1.6	Quality Assessment Data.....	7
1.8	Abbreviations and Acronyms	2	3.1.7	Sample Qualification.....	7
1.9	Terms and Definitions	2	3.1.8	Production Data	7
1.10	Product Classification	2	3.1.9	Customer Test Data.....	7
1.10.1	Specification Sheet Description	2	3.1.10	Internal Assessment.....	7
1.10.2	Metal Base Type and Nominal Thickness.....	3	3.1.11	Individual Customer Audit.....	7
1.10.3	Nominal Thickness of Dielectric Layer.....	3	3.1.12	Independent Third Party Assessment	7
1.10.4	Metal Cladding Type and Nominal Weight/ Thickness	3	3.1.13	AABUS	7
1.10.4.1	Metal Cladding Grade	3	3.2	Specification Sheets	8
1.10.4.2	Nominal Weight/Thickness of Metal Foil.....	3	3.3	Manufacturer Quality Profile	8
1.10.5	Surface Quality Class.....	5	3.4	Qualification Testing	8
1.10.6	Color.....	5	3.5	Verification of Manufacturer's Quality System	8
1.10.6.1	Contrast Agents.....	5	3.6	Materials	10
2	APPLICABLE DOCUMENTS	5	3.6.1	Metal Cladding	10
2.1	IPC	5	3.6.2	Reinforcement Fabric.....	10
2.2	IPC-TM-650 Test Methods	5	3.6.3	Polymer Systems	10
2.3	National Conference of Standards Laboratories (NCSL)	6	3.6.4	Metal Base	10
2.3.1	ANSI/NCSL Z540-3-2006	6	3.7	General Requirements	10
2.4	International Standards	6	3.7.1	Fabricated Sheets and Panels.....	10
2.4.1	ISO 10012-1.....	6	3.7.1.1	Fabricated Metal Base Laminate Sheet Material	10
2.5	Underwriters Laboratories (UL)	6	3.7.2	Inspection Lot	10
2.5.1	UL94.....	6	3.7.2.1	Inspection Lot for Metal Base Laminate	10
2.6	European Union	6	3.7.2.2	Preparation of Samples	10
2.6.1	Restrictions of Hazardous Substances (RoHS) for Electrical and Electronic Equipment Directive.....	6	3.7.2.3	Etching Process and Etchant Removal for Copper Foil Specimens	10
			3.7.2.4	Standard Laboratory Conditions.....	10
			3.7.3	Visual Properties.....	10
			3.7.3.1	Metal Base Laminate Visual Properties	10
			3.7.3.1.1	Foil and Metal Base Indentations.....	11

3.7.3.1.2	Wrinkles	11	3.9.9	X/Y CTE	15
3.7.3.1.3	Scratches on Foil and Metal Base	11	3.9.10	Decomposition Temperature T _d (Optional Test)	16
3.7.3.1.4	Surface Finish of Foil after Curing	11	3.10	Electrical Requirements	16
3.7.3.1.5	Surface and Subsurface Imperfections	11	3.10.1	Electrical Requirements of Laminate Materials	16
3.7.3.1.6	Inclusions	12	3.10.1.1	Permittivity	16
3.7.4	Dimensional	12	3.10.1.2	Loss Tangent	16
3.7.4.1	Length and Width	12	3.10.1.3	Volume Resistivity	16
3.7.4.1.1	Length and Width of Laminate	12	3.10.1.4	Surface Resistivity	16
3.7.4.2	Thickness	12	3.10.1.5	Arc Resistance	16
3.7.4.2.1	Class K, L and M Metal Base Laminate Materials	12	3.10.1.6	Dielectric Breakdown	16
3.7.4.2.2	Class D Metal Base Laminate Materials	12	3.10.1.7	Electric Strength	16
3.7.4.2.3	Class K, L and M Metal Base Laminate Materials	13	3.10.1.8	Dielectric Withstand Voltage (HI-POT)	16
3.7.4.2.4	Thickness Tolerance of Metal Base Laminate Materials	13	3.10.1.9	Comparative Tracking Index (CTI)	16
3.7.4.3	Bow and Twist of Metal Base Laminate Materials	13	3.11	Environmental Requirements	16
3.7.4.3.1	Sheets and Panels with Both Dimensions >300 mm [11.81 in.]	13	3.11.1	Moisture Absorption	16
3.7.4.3.2	Panels with One or Both Dimensions < 300 mm [11.81 in.]	14	3.11.2	Fungus Resistance (Optional Test)	16
3.7.5	Coefficient of Thermal Expansion (CTE) (Optional Test)	14	3.11.3	Pressure Vessel (Optional Test)	16
3.7.6	Z-Axis CTE	14	3.11.4	Total Halogen Content (Optional Test)	16
3.8	Physical Requirements	14	3.11.5	Conductive Anodic Filament (CAF) Growth (Optional Test)	16
3.8.1	Physical Requirements of Laminate Materials ...	14	3.12	Substitutability	17
3.8.1.1	Peel Strength	14	3.12.1	Substitutability of Classes of Pits and Dents	17
3.8.1.1.1	Peel Strength after Thermal Stress	14	3.12.2	Substitutability of Classes of Thickness Tolerance	17
3.8.1.1.2	Peel Strength at Elevated Temperature	14	3.13	Marking	17
3.8.1.1.3	Peel Strength after Process Chemicals (Optional Test)	14	3.13.1	Marking	17
3.8.1.2	Dimensional Stability	14	3.13.3	Marking of Shipping Containers	17
3.8.1.3	Thermal Conductivity W/(m ² K)	14	3.14	Workmanship	17
3.8.1.4	Thermal Impedance °C cm ² /W (per 25.4 microns)	14	3.15	Material Safety	17
3.9	Chemical Requirements	15	4	QUALITY ASSURANCE PROVISIONS	18
3.9.1	Flammability	15	4.1	Quality System	18
3.9.2	Thermal Stress	15	4.2	Responsibility for Inspection	18
3.9.3	Solderability	15	4.2.1	Test Equipment and Inspection Facilities	18
3.9.4	Chemical Resistance (Optional Test)	15	4.3	Qualification Testing	18
3.9.5	Metal Surfaces Cleanability	15	4.3.1	Samples	18
3.9.6	Glass Transition Temperature (T _g)/Delta T _g	15	4.3.2	Frequency	18
3.9.7	Time to Delaminate (TMA)	15	4.3.3	Laminator Qualification Profile	18
3.9.8	Z-Axis CTE	15	4.3.4	Changes in Composition	18
			4.3.5	Qualification Data Retention	18
			4.4	Quality Conformance Inspection	18
			4.4.1	Frequency	18

4.4.2	Acceptance Criteria.....	18			
4.4.3	Rejected Lots.....	19			
4.4.4	Conformance Data Retention.....	19			
4.4.5	Certificate of Conformance	19			
4.5	Statistical Process Control (SPC)	19			
5	PREPARATION FOR DELIVERY	20			
5.1	Packaging Materials Metal Base Materials.....	20			
5.2	Authorized Distributors	20			
6	NOTES.....	20			
6.1	Ordering Information.....	20			
6.1.1	Ordering Data for Metal Base Laminate Materials	20			
6.2	New Materials.....	20			
7	KEYWORDS	20			
7.1	Keyword Search Terms (Electronic/Soft Copy Searches).....	20			
7.2	Segmented Keyword Search Terms and All Specification Sheets that Use the Specific Keywords for Searching.....	21			
APPENDIX A	Abbreviations and Acronyms	29			
Figures					
Figure 1-1	Laminate Dielectric Thickness	3			
Tables					
Table 1-1	Metal Base Types.....	4			
Table 1-2	Metal Cladding Types	4			
Table 1-3	Copper Foil Weight and Thickness	4			
Table 3-1	Reference Information and Test Frequency of Metal Base Laminate	8			
Table 3-2	Point Value for Longest Dimensions of Indentation	11			
Table 3-3	Surface Quality Classification.....	11			
Table 3-4	Permissible Variation in Length and Width of Metal Base Laminate	12			
Table 3-5	Thickness and Tolerances for Metal Base Laminate.....	13			
Table 3-6	Permissible Bow and Twist for Metal Base Laminate (%).....	13			
Table 3-7	Flammability Requirements.....	15			
Table 4-1	Quality Conformance Plan for Monthly, Quarterly and Annual Tests – Metal Base Laminate	18			